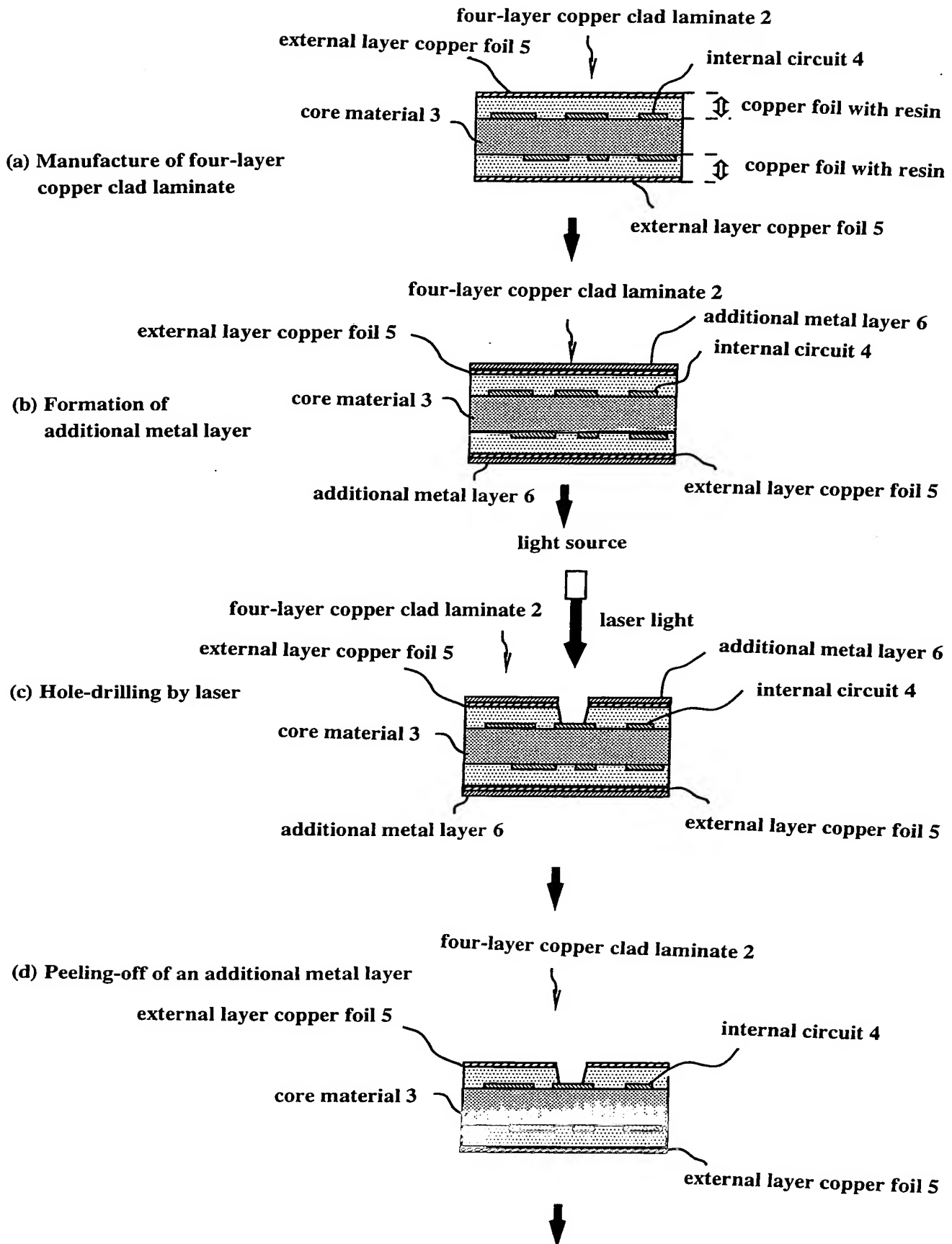
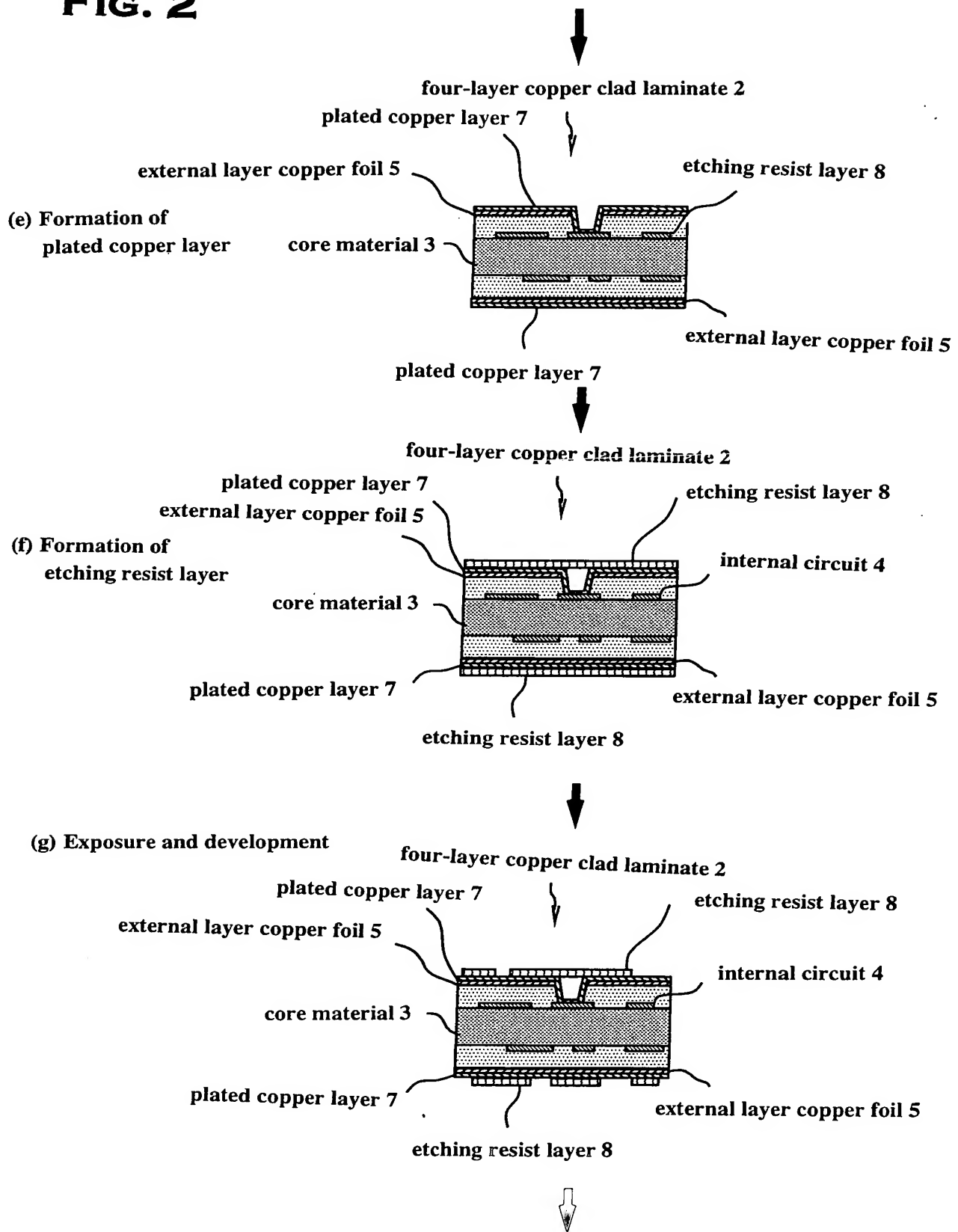


**FIG. 1**



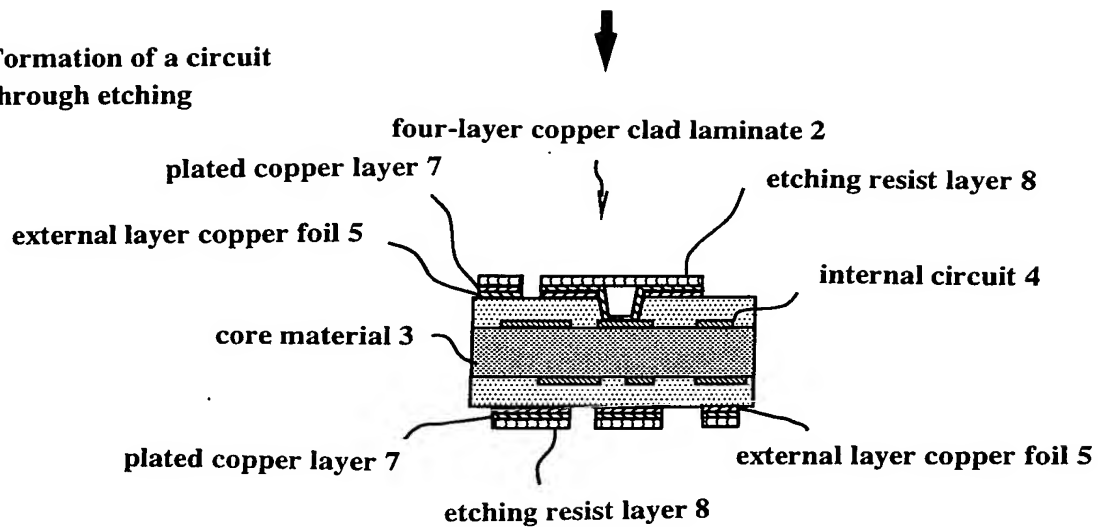
10082154.022602

**FIG. 2**



**FIG. 3**

(h) Formation of a circuit through etching



(i) Peeling-off of etching resist layer

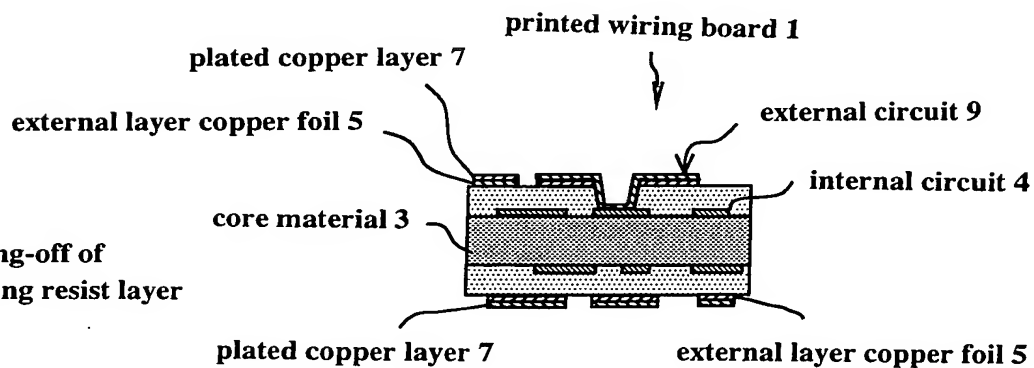


FIG. 4

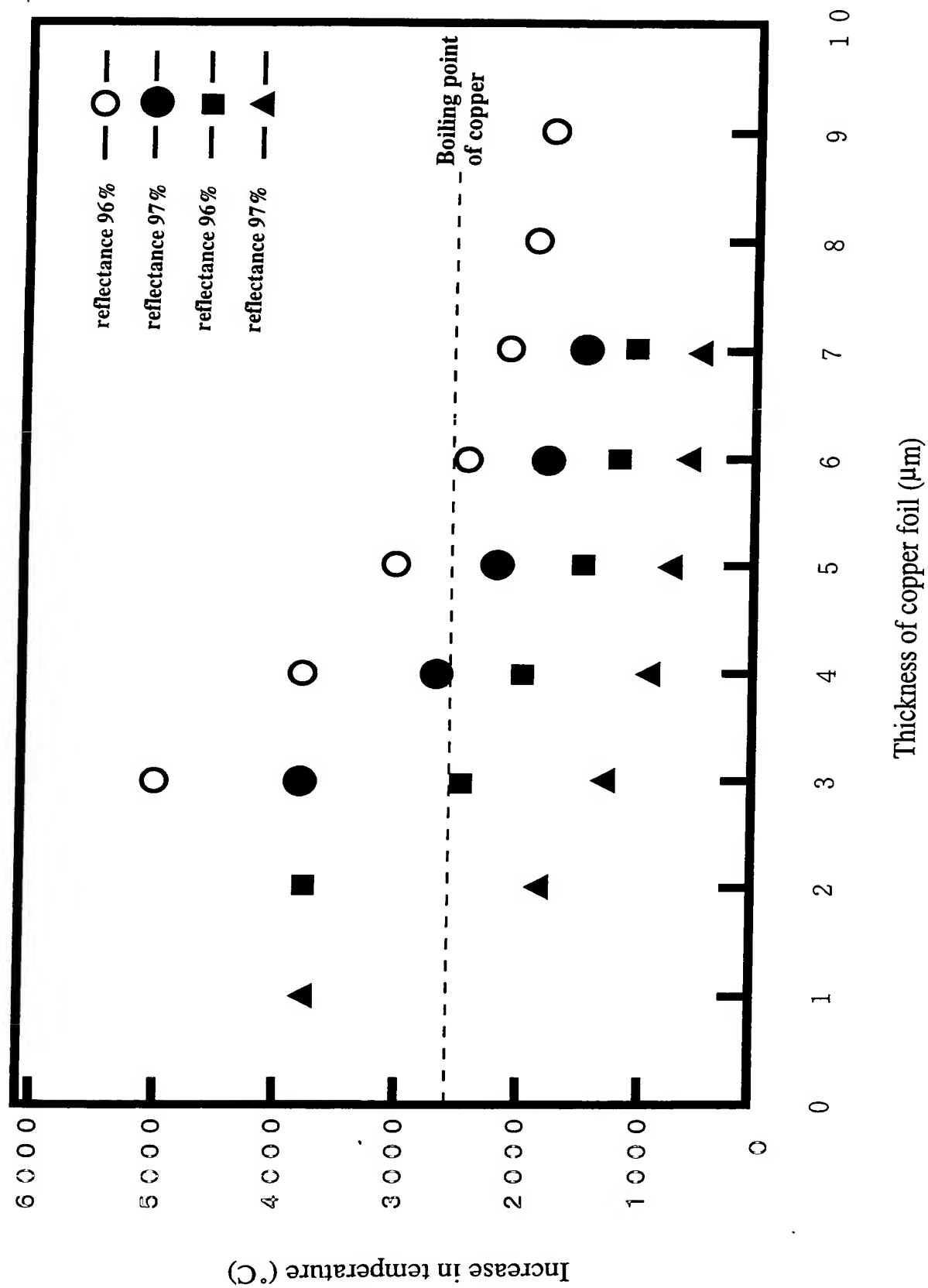
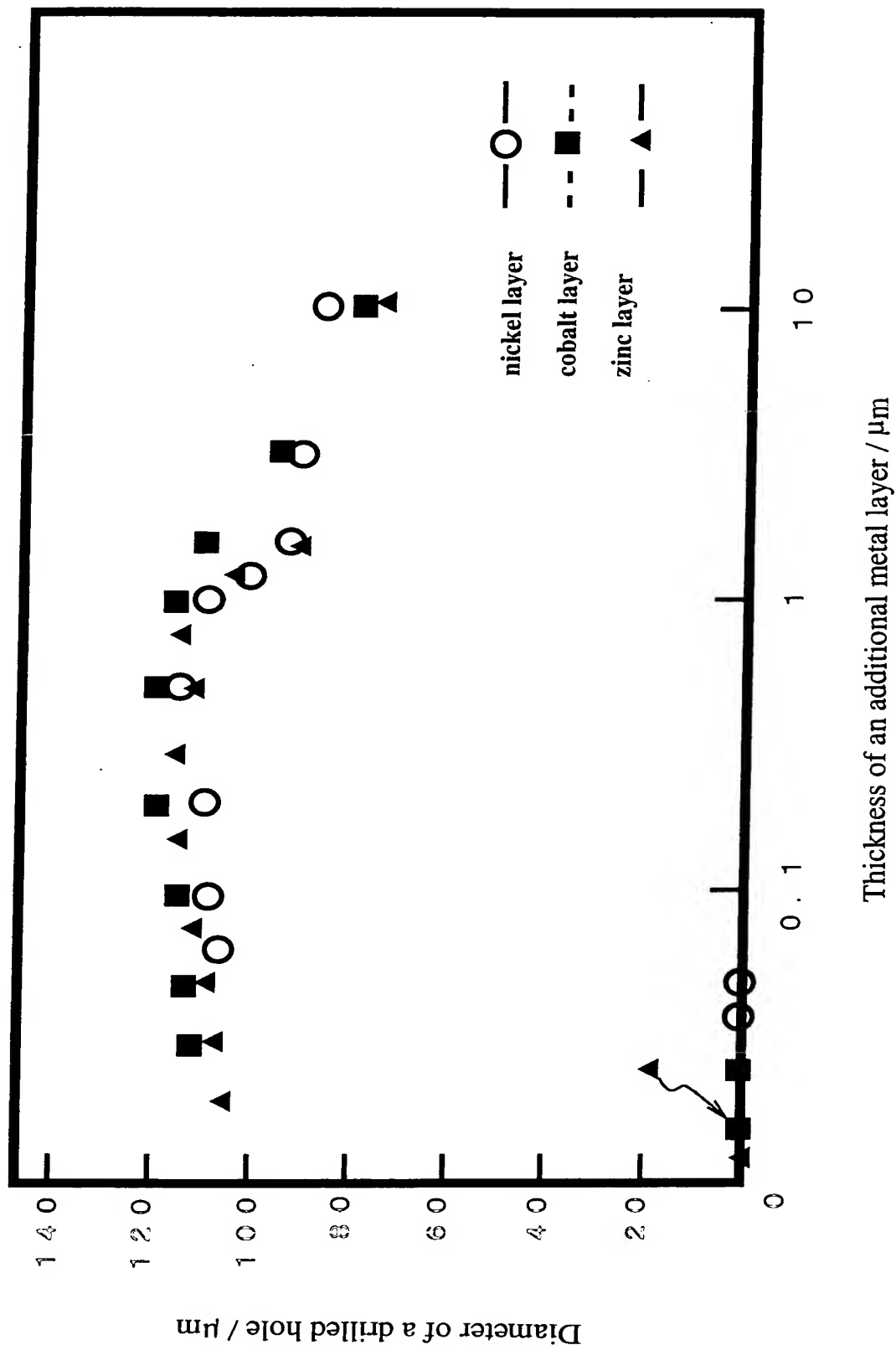
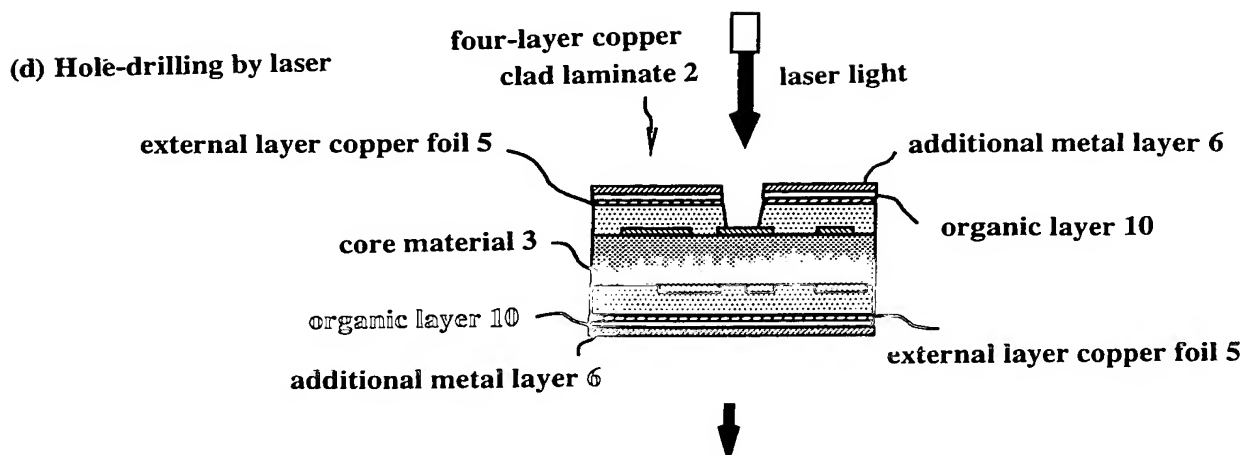
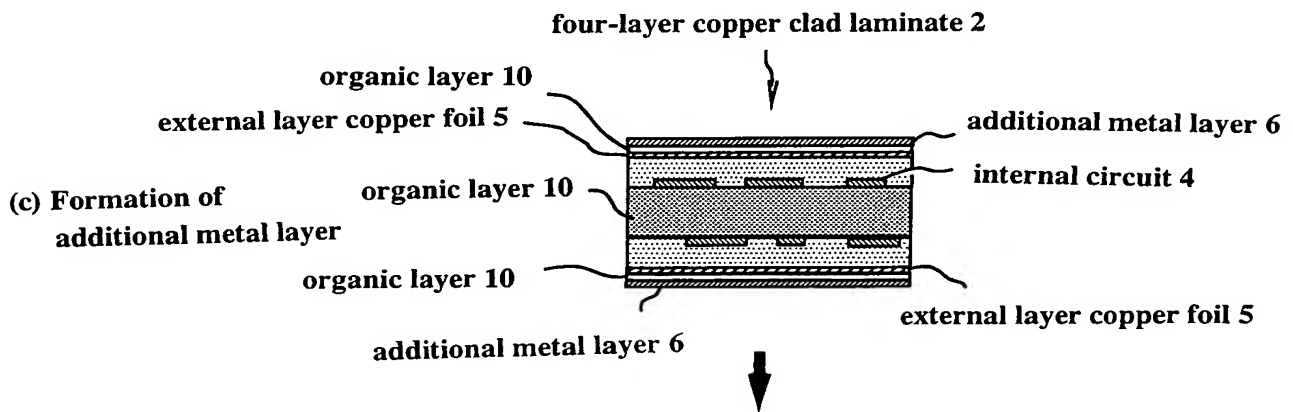
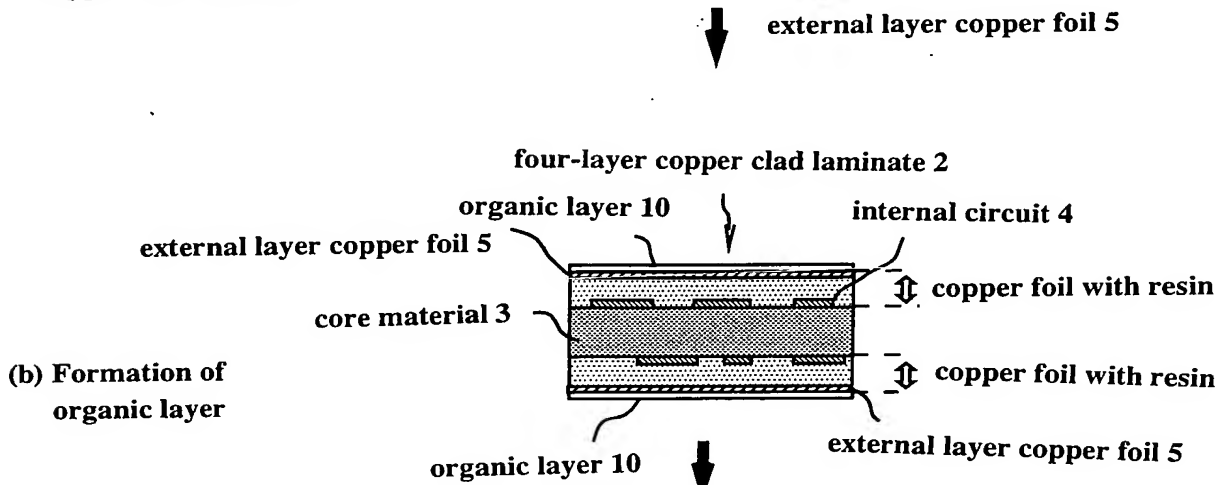
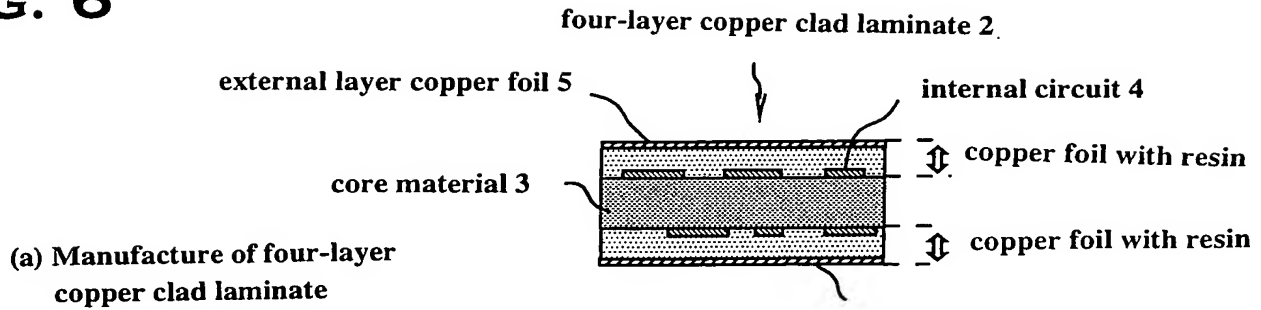


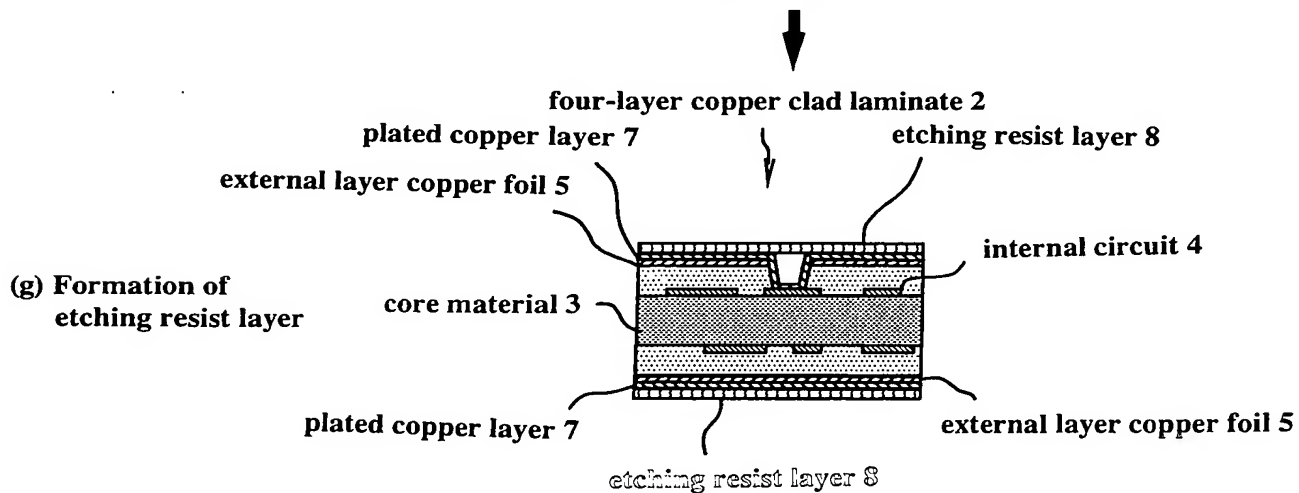
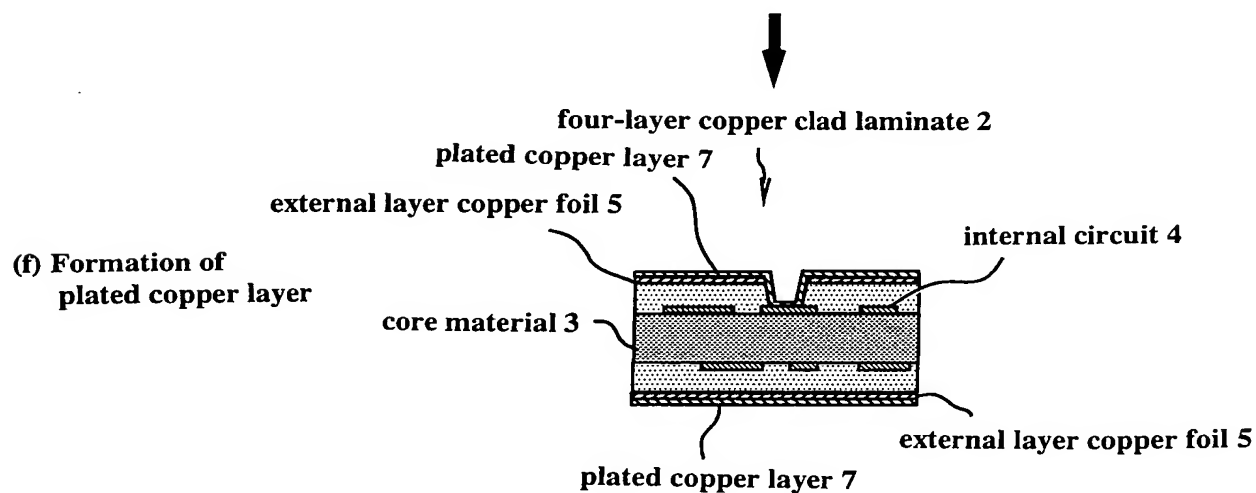
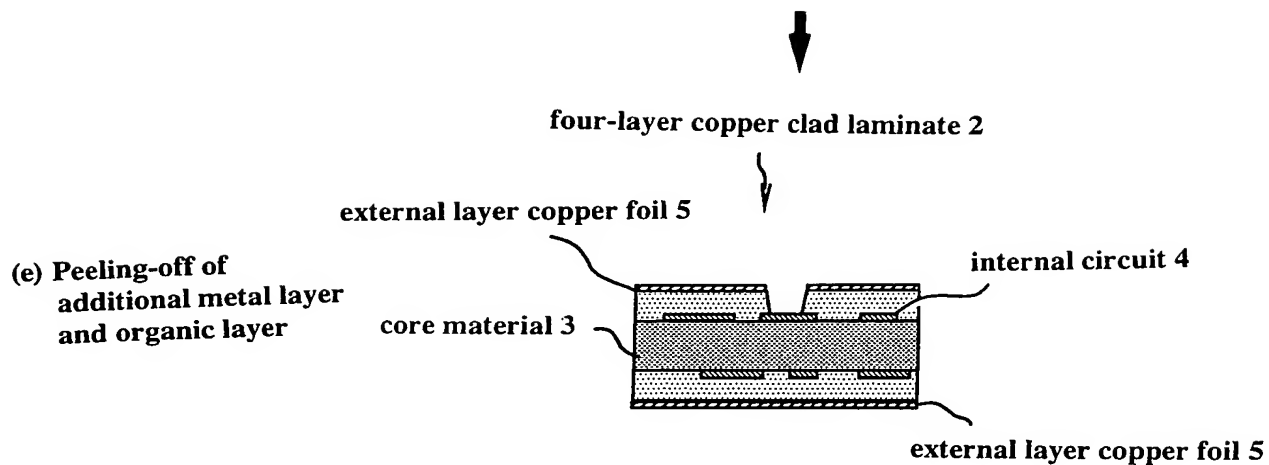
FIG. 5



**FIG. 6**

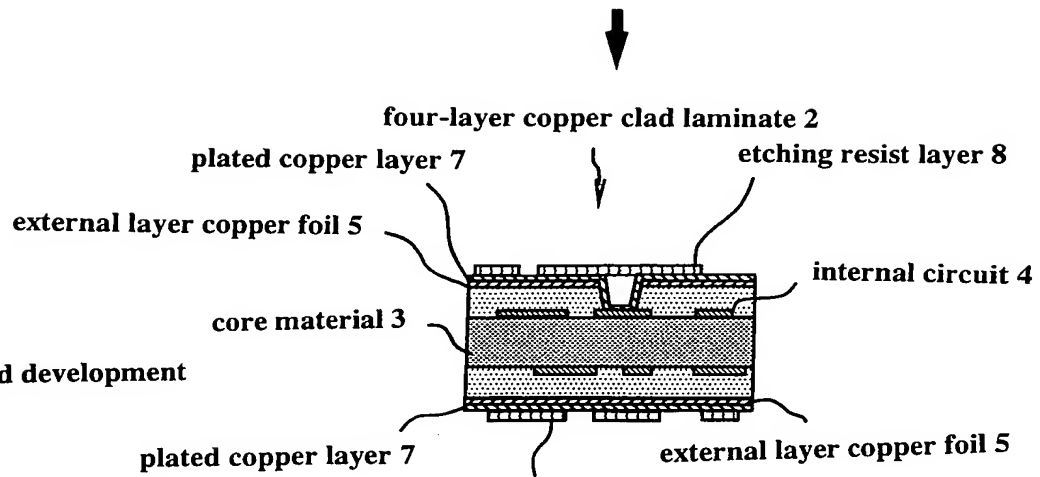


**FIG. 7**

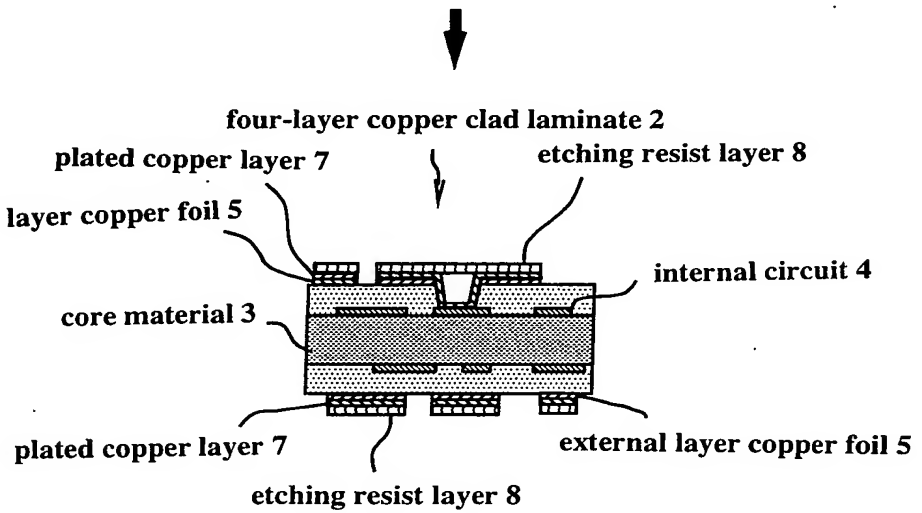


**FIG. 8**

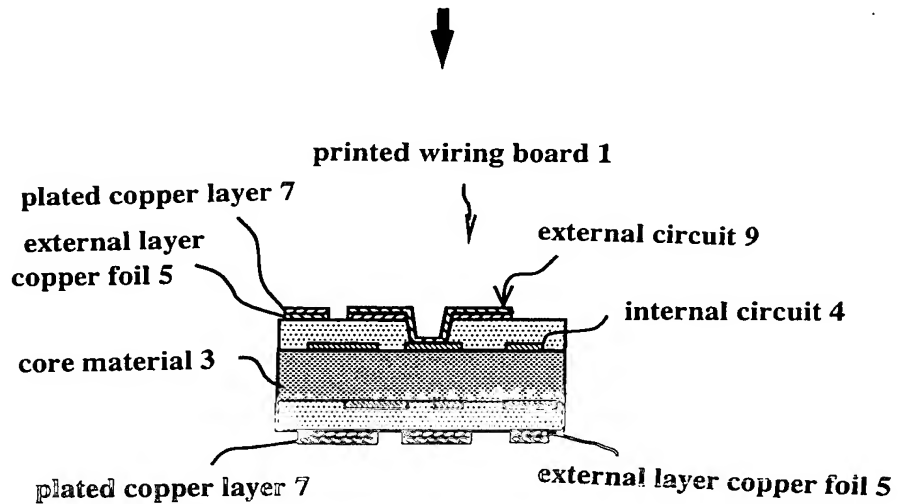
(h) Exposure and development



(i) Formation of a circuit through etching



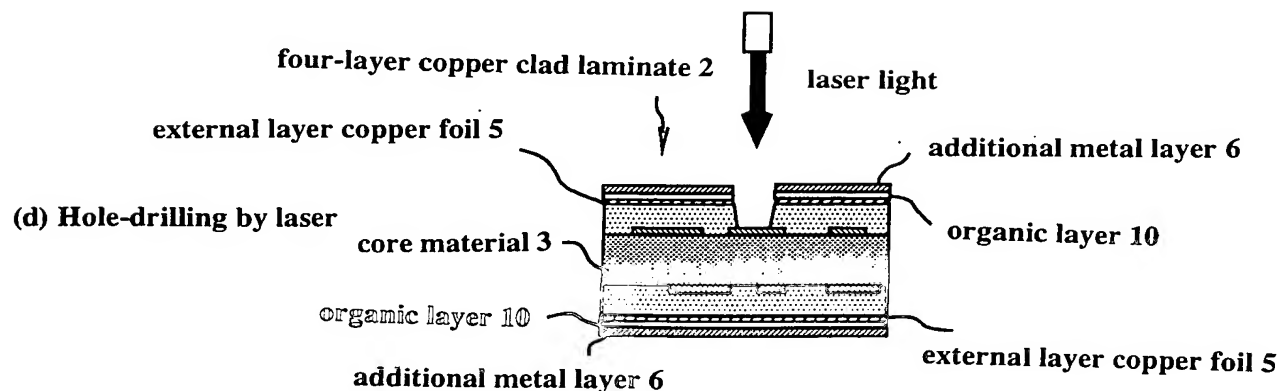
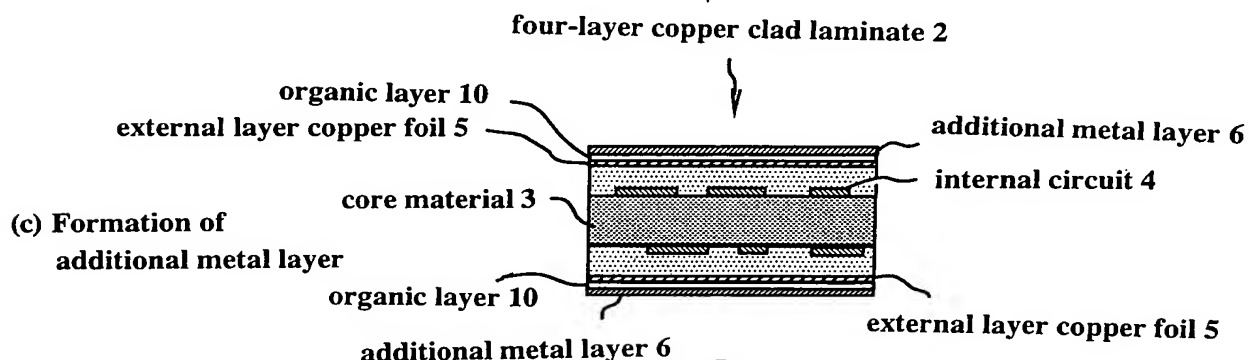
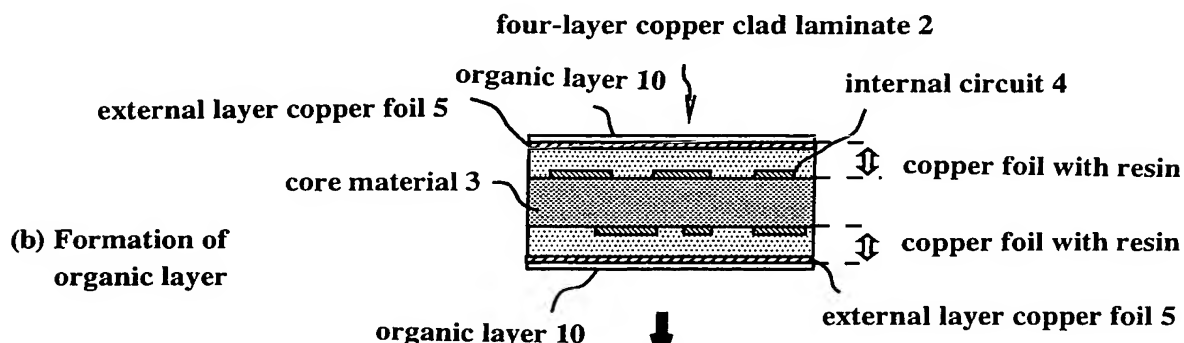
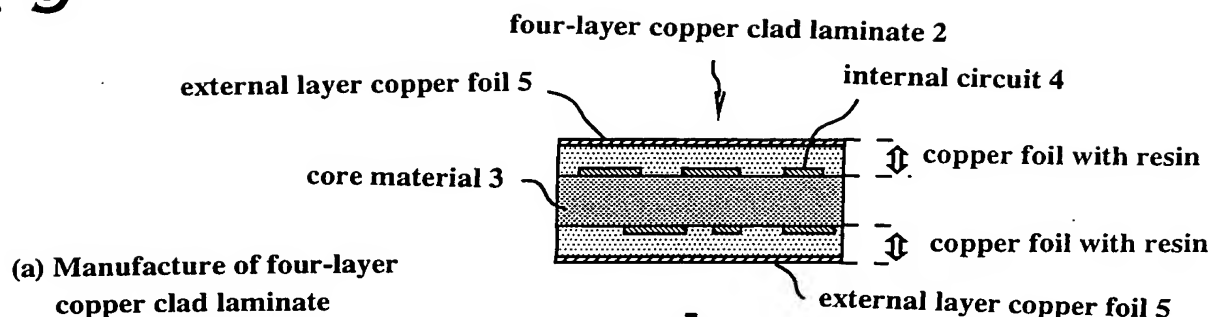
(j) Peeling-off of etching resist layer



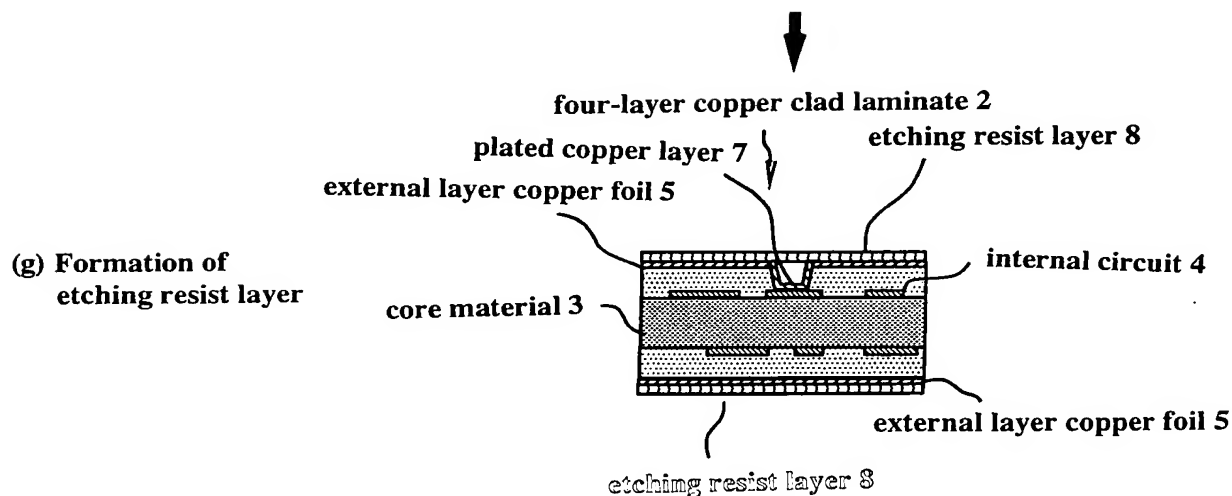
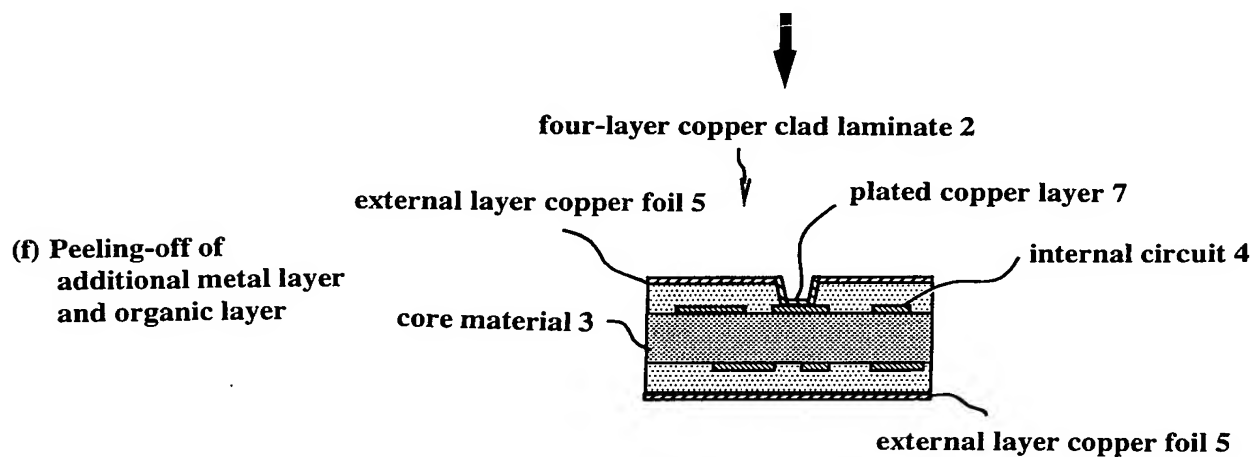
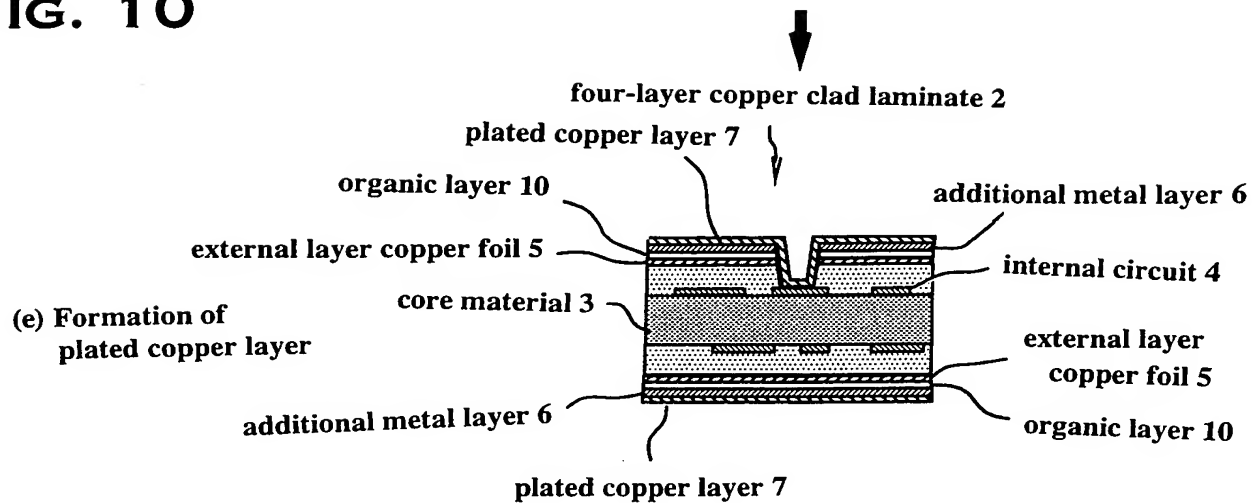
10082154-022502



# FIG. 9



**FIG. 10**



**FIG. 11**

